

物质成分分析



DEVICE	Package Type	Material	Supplier	Type	Compisition	CAS No.	% of weight	Appendix	Weight(mg)	ICP报告	MSDS
LS98003-D	DFN-8L-2X2X0.75_P0.5	Lead frame	ASM	DFN-8L-2X2-D_71X43_1Block_No Tape	Copper(Cu)	7440-50-8	96.24-97.325		4.116		
					Iron(Fe)	7439-89-6	2.10 ~ 2.60				
					Lead (Pb)	7439-92-1	0.01 Max.				
					Phosphorus(P)	7723-14-0	0.015 ~ 0.150				
					Zinc(Zn)	7440-66-6	0.050 ~ 0.200				
					Silver(Ag)	7440-22-4	0.5-0.8				
		DAF	Henkel	ATB-F125E	Modified Epoxy Resin	Proprietary	20- < 30 %		0.041		
					Poly[oxy[(2-oxiranyl)-1,2-cyclohexanediyl]], a-hydro_x005f_x005f_x0002_w-hydroxy-, ether with 2-ethyl-2-(hydroxymethyl)-1,3-propanediol (3:1)	244772-00-7	1- < 10 %				
					Phenol-formaldehyde polymer	9003-35-4	1- < 10 %				
					reaction product: bisphenol-A-(epichlorhydrin)	25068-38-6	1- < 10 %				
		Wire	Nippon	AuPdCu EX1p-H φ20μm	Copper	7440-50-8	≥96.55		0.016		
					Palladium	7440/5/3	≤3.1				
					Gold	7440-57-5	≤0.35				
		Compound	Showa Denko	CEL-9240HF10XD-D10	环氧树脂1	商业机密	0.5~8%		4.66		
					环氧树脂2	商业机密	0.5~6%				
					硬化剂	商业机密	3~8%				
					催化剂	商业机密	<1%				
					碳黑	1333-86-4	<0.3%				
					二氧化硅1	60676-86-0	77~82%				
		Sn	云南锡业	锡球 Sn99.99(99.90%)	Tin	7440-31-5	99.90-99.99%		0.154		
		Die	NA	NA					0.467		
								Total=	8.987		